

ABSTRACT OF THE DISCLOSURE

There is disclosed a manufacturing method of a piezoelectric/electrostrictive film type device including a ceramic substrate, a piezoelectric/electrostrictive operation
5 portion containing a lower electrode, a piezoelectric/
electrostrictive layer, and upper electrode stacked on the substrate, and the piezoelectric/electrostrictive layer being formed beyond at least one of electrodes to form projected portions at its ends, the method comprising the steps of
10 forming the piezoelectric/electrostrictive layer beyond at least one of electrodes to project ends of the layer; applying a coating liquid in an amount sufficient to make the coating liquid permeate through a gap between at least a projected portion of the piezoelectric/electrostrictive layer
15 and the substrate, and coat a predetermined portion of said at least one of electrodes; and drying thus applied coating liquid to form a coupling member to couple a projected portion of the piezoelectric/electrostrictive layer. The piezoelectric/electrostrictive operation portion may be a
20 multilayered structure.